

HDI PCB Technics Capacity

No.	Item	Description	DataSheet
1	Material	Brand	SY、ITEQ、KB、NOUYA
2	HDI Construction		1+N+1、2+N+2、3+N+3、4+N+4、5+N+5、6+N+6、Anylayer
3	Construction order		N+N、N+X+N、1+(N+X+N)+1
4	Layer		1-40Layers
5	Min Pattern Width/Spacing	Unit:mil	2/2
6	Min Mechanical Hole	Unit:mm	0.15mm
7	Min Thickness of Core Board	Unit:mil	2mil
8	Laser Hole	Unit:mm	0.075mm-0.1mm
9	Min thickness of PP	Unit:mil	2mil
10	Max diameter of resin plug hole	Unit:mm	0.4mm
11	Electroplating to fill holes		Can do it.
12	Electroplating to fill holes size	Unit:mil	3-5mil
13	hole pile pad/hole pile hole/pad hole(VOP)	mil	Can do it.
14	The distance from the wall of via hole to the pattern	mil	7mil

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15	Laser drilling hole accuracy	mil	0.025mm
16	Min BGA pad center distance	mil	0.3mm
17	Min SMT	mil	0.25mm
18	Plating hole-filling sag	mil	≤10um
19	Back drilled/countersink hole tolerance	mil	±0.05mm
20	Through-hole plating penetration capacity	Rate	16:1
21	Blind hole plating penetration capacity	Rate	1.2:1
22	BGA min PAD	Unit:mil	0.2
23	Min Buried Hole(Mechanical Hole)	Unit:mil	0.2
24	Min Buried Hole(Laser Hole)	Unit:mil	0.1
25	Min Blind Hole(Laser Hole)	Unit:mil	0.1
26	Min Blind Hole(Mechanical Hole)	Unit:mil	0.2
27	Minimum spacing between laser blind hole and mechanical buried hole	Unit:mil	0.2
28	Min Laser Hole	Unit:mil	0.10(depth≤55um)、0.13(depth≤100um)
29	MinBGA pad center distance	Unit:mil	0.3

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30	Interlaminar alignment	Unit:mil	±0.05mm(±0.002")
			The distance from the wall of via hole to the pattern
19	Back drilled/countersink hole tolerance	mil	±0.05mm
20	Through-hole plating penetration capacity	Rate	16:1
21	Blind hole plating penetration capacity	Rate	1.2:1
22	BGA min PAD	Unit:mil	0.2
23	Min Buried Hole(Mechanical Hole)	Unit:mil	0.2
24	Min Buried Hole(Laser Hole)	Unit:mil	0.1
25	Min Blind Hole(Laser Hole)	Unit:mil	0.1
26	Min Blind Hole(Mechanical Hole)	Unit:mil	0.2
27	Minimum spacing between laser blind hole and mechanical buried hole	Unit:mil	0.2
28	Min Laser Hole	Unit:mil	0.10(depth≤55um)、0.13(depth≤100um)
29	MinBGA pad center distance	Unit:mil	0.3
30	Interlaminar alignment	Unit:mil	±0.05mm(±0.002")
			The distance from the wall of via hole to the pattern